US00D868123S

(12) **United States Design Patent**
Bell et al.

(10) **Patent No.: US D868,123 S**
(45) **Date of Patent: ** Nov. 26, 2019**

(54) **WIRE BONDING WEDGE TOOL**

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(**) Term: **15 Years**

(21) Appl. No.: **29/588,393**

(22) Filed: **Dec. 20, 2016**

(51) **LOC (12) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/144**

(58) **Field of Classification Search**
USPC D8/14, 14.1, 29, 30; D15/144, 144.1, D15/144.2; D24/187
CPC .. B23K 20/004; B23K 20/005; B23K 20/106; H01L 24/85
See application file for complete search history.

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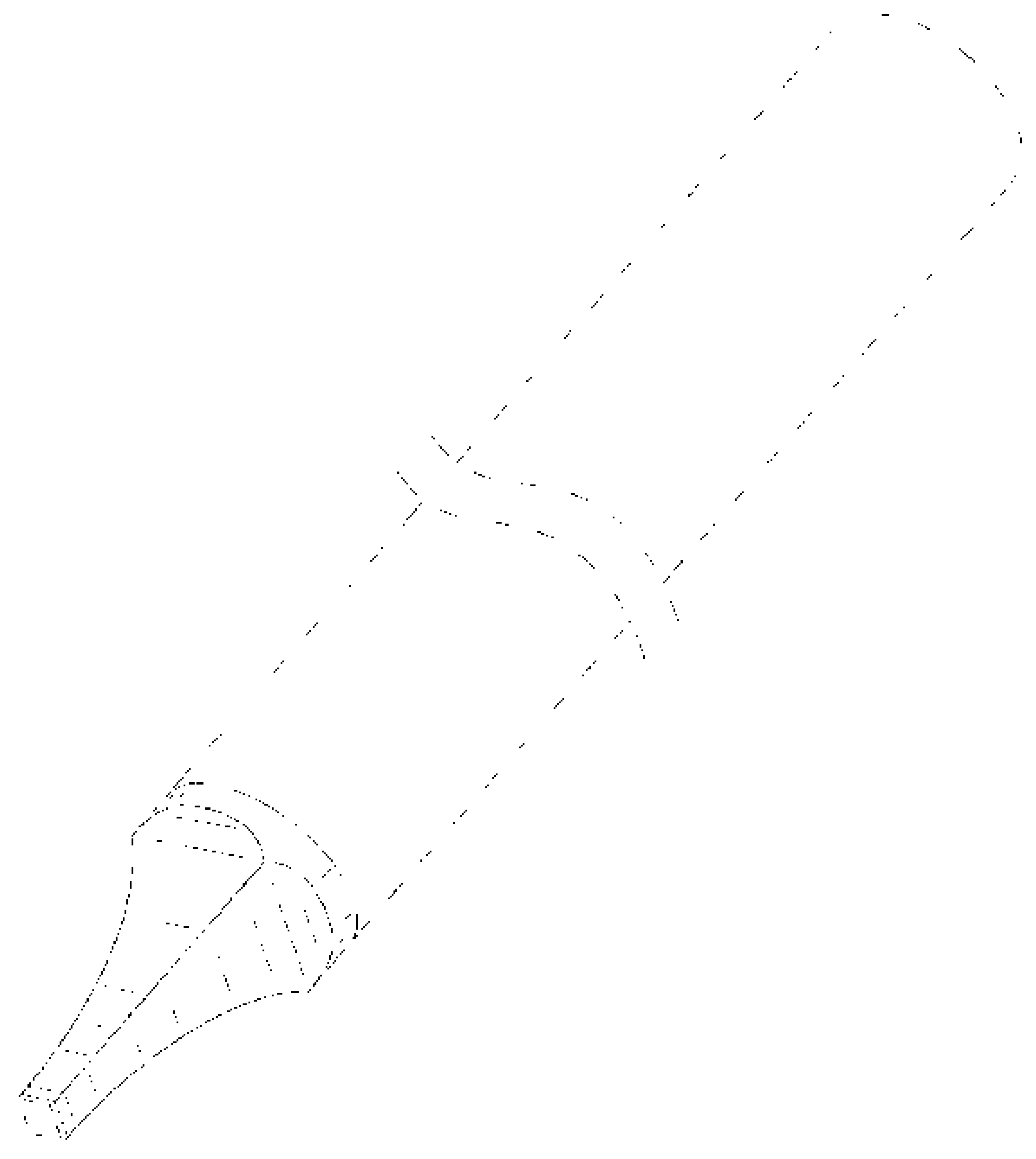

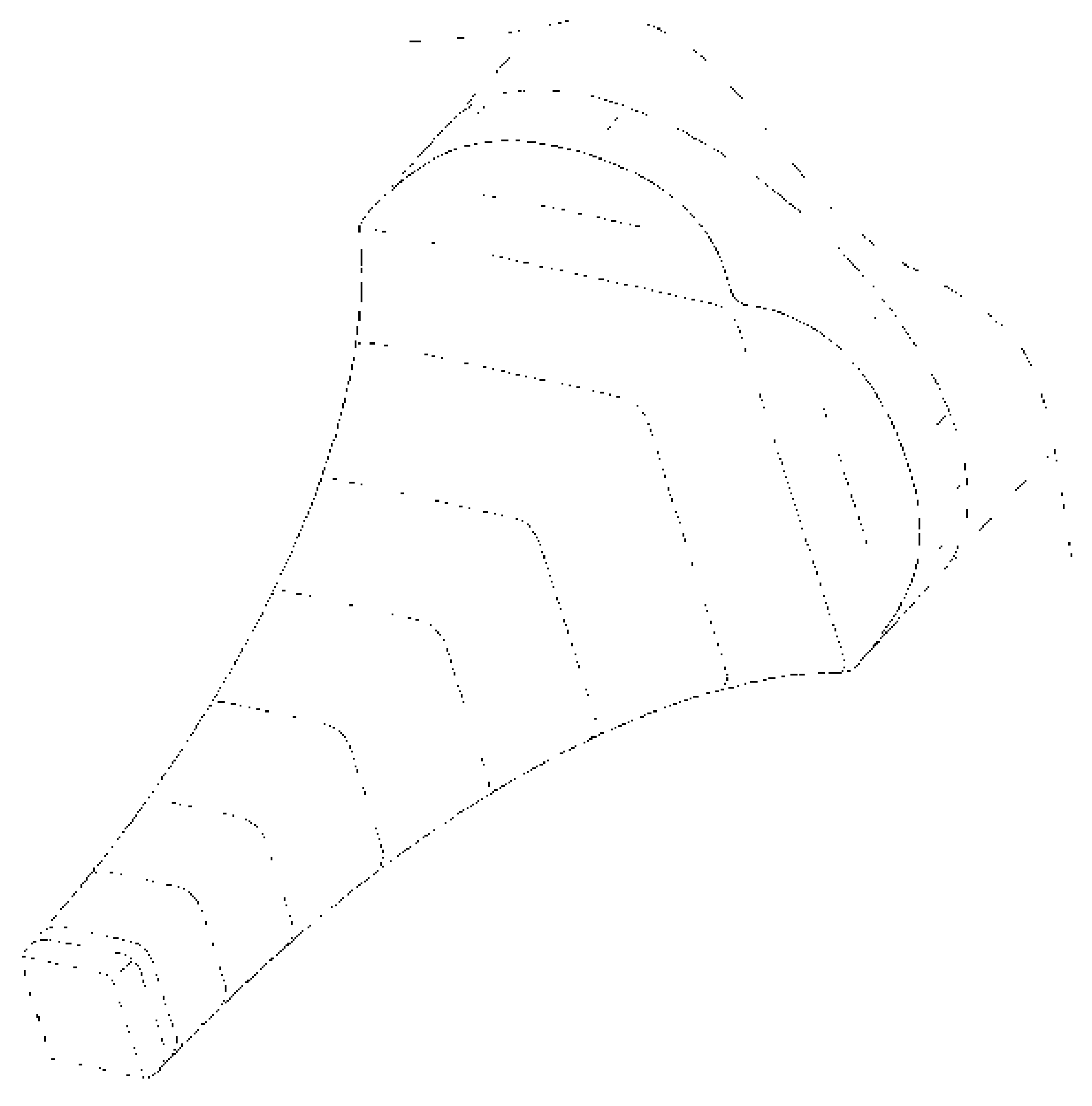

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(57) CLAIM

The ornamental design for a wire bonding wedge tool, as shown and described.

DESCRIPTION

FIG. **1** depicts a perspective view of a wire bonding wedge tool illustrating a first embodiment of our new design.
FIG. **2** depicts a front side elevation view of the wire bonding wedge tool of FIG. **1**.
FIG. **3** depicts a right side elevation view of the wire bonding wedge tool of FIG. **1**.
FIG. **4** depicts a rear side elevation view of the wire bonding wedge tool of FIG. **1**.
FIG. **5** depicts a left side elevation view of the wire bonding wedge tool of FIG. **1**.
FIG. **6** depicts a bottom plan view of the wire bonding wedge tool of FIG. **1**.
FIG. **7** depicts a top plan view of the wire bonding wedge tool of FIG. **1**.
FIG. **8** depicts an enlarged perspective view of a tip of the wire bonding wedge tool of FIG. **1**.
FIG. **9** depicts an enlarged front side elevation view of the tip of the wire bonding wedge tool of FIG. **1**.
FIG. **10** depicts an enlarged right side elevation view of the tip of the wire bonding wedge tool of FIG. **1**.
FIG. **11** depicts an enlarged rear side elevation view of the tip of the wire bonding wedge tool of FIG. **1**.
FIG. **12** depicts an enlarged left side elevation view of the tip of the wire bonding wedge tool of FIG. **1**.
FIG. **13** depicts an enlarged bottom plan view of the tip of the wire bonding wedge tool of FIG. **1**.
FIG. **14** depicts a perspective view of a wire bonding wedge tool illustrating a second embodiment of our new design.
FIG. **15** depicts a front side elevation view of the wire bonding wedge tool of FIG. **14**.
FIG. **16** depicts a right side elevation view of the wire bonding wedge tool of FIG. **14**.
FIG. **17** depicts a rear side elevation view of the wire bonding wedge tool of FIG. **14**.
FIG. **18** depicts a left side elevation view of the wire bonding wedge tool of FIG. **14**.
FIG. **19** depicts a bottom plan view of the wire bonding wedge tool of FIG. **14**.
FIG. **20** depicts a top plan view of the wire bonding wedge tool of FIG. **14**.
FIG. **21** depicts an enlarged perspective view of a tip of the wire bonding wedge tool of FIG. **14**.
FIG. **22** depicts an enlarged front side elevation view of the tip of the wire bonding wedge tool of FIG. **14**.

FIG. **23** depicts an enlarged right side elevation view of the tip of the wire bonding wedge tool of FIG. **14**.

FIG. **24** depicts an enlarged rear side elevation view of the tip of the wire bonding wedge tool of FIG. **14**.

FIG. **25** depicts an enlarged left side elevation view of the tip of the wire bonding wedge tool of FIG. **14**; and,

FIG. **26** depicts an enlarged bottom plan view of the tip of the wire bonding wedge tool of FIG. **14**.

Features shown in dash-dot lines are boundaries that form no part of the claimed design.

Features shown in broken lines form no part of the claimed design.

1 Claim, 20 Drawing Sheets

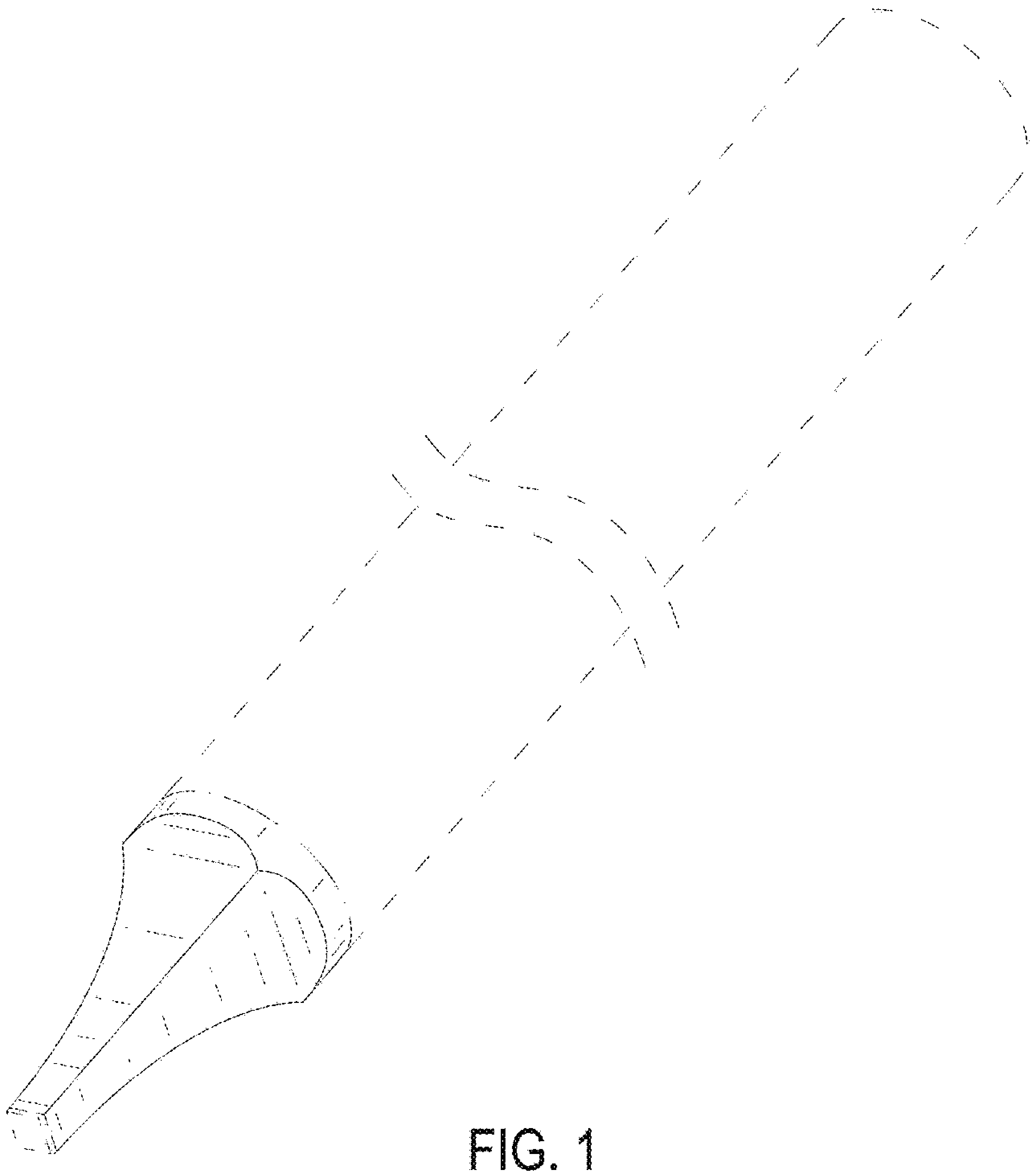


FIG. 1

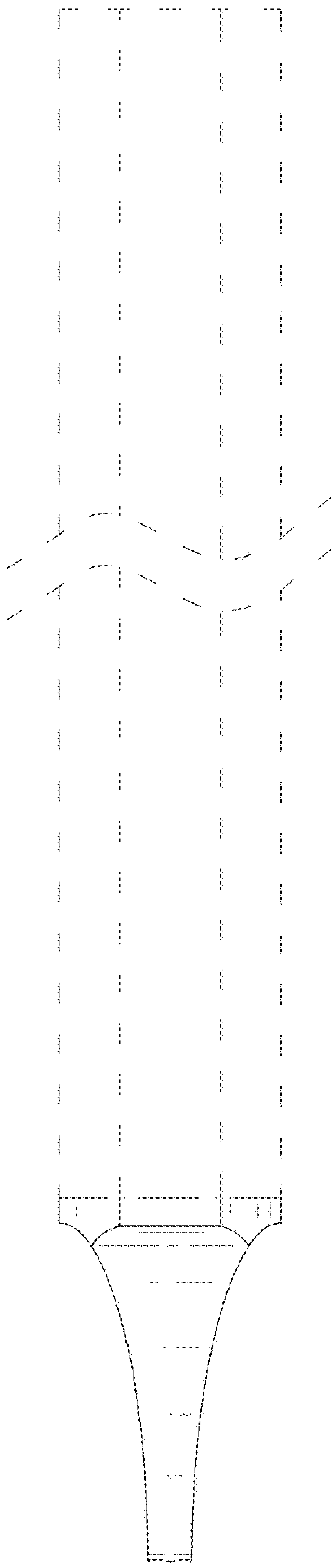
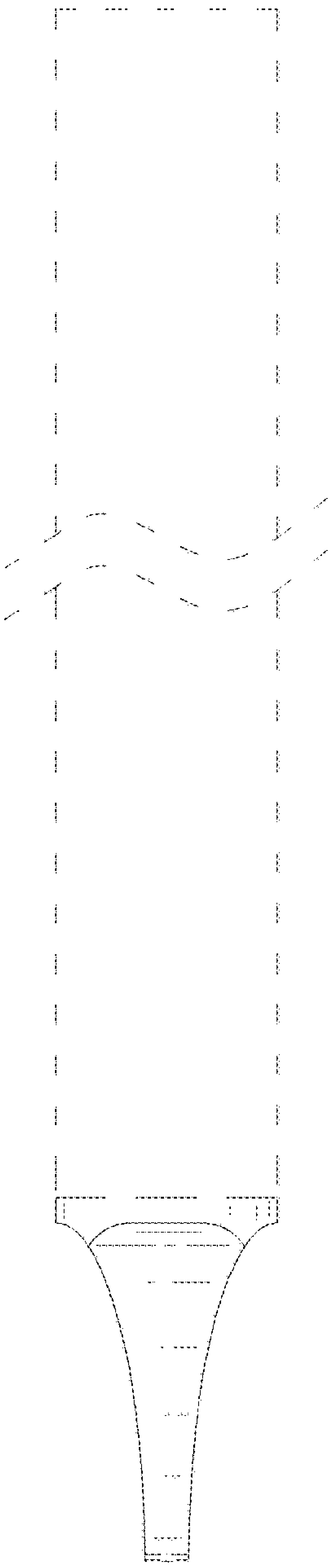


FIG. 2

FIG. 3



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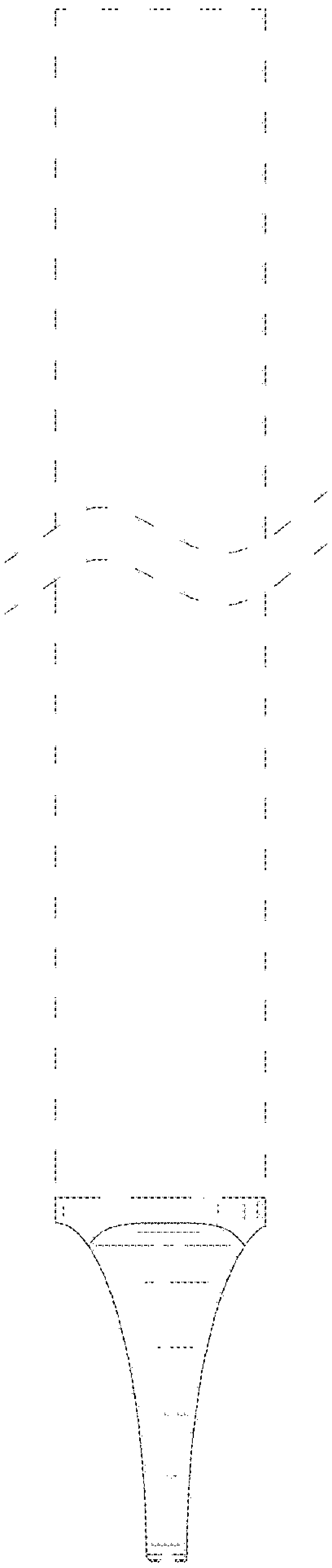

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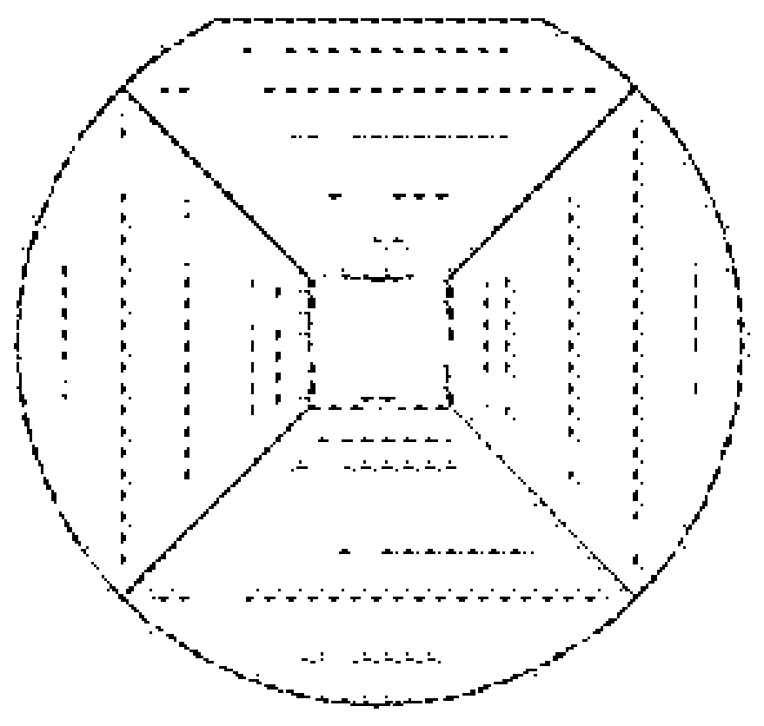

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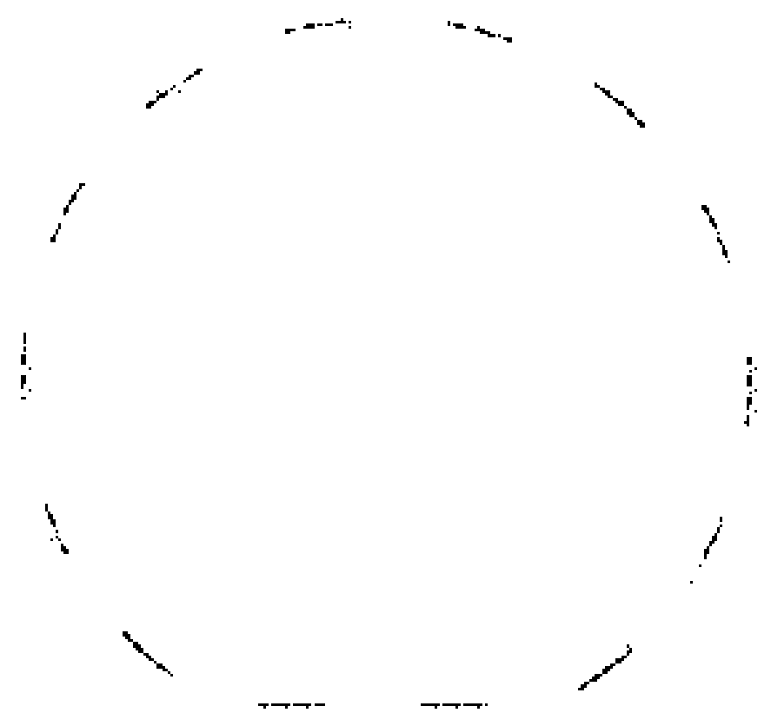

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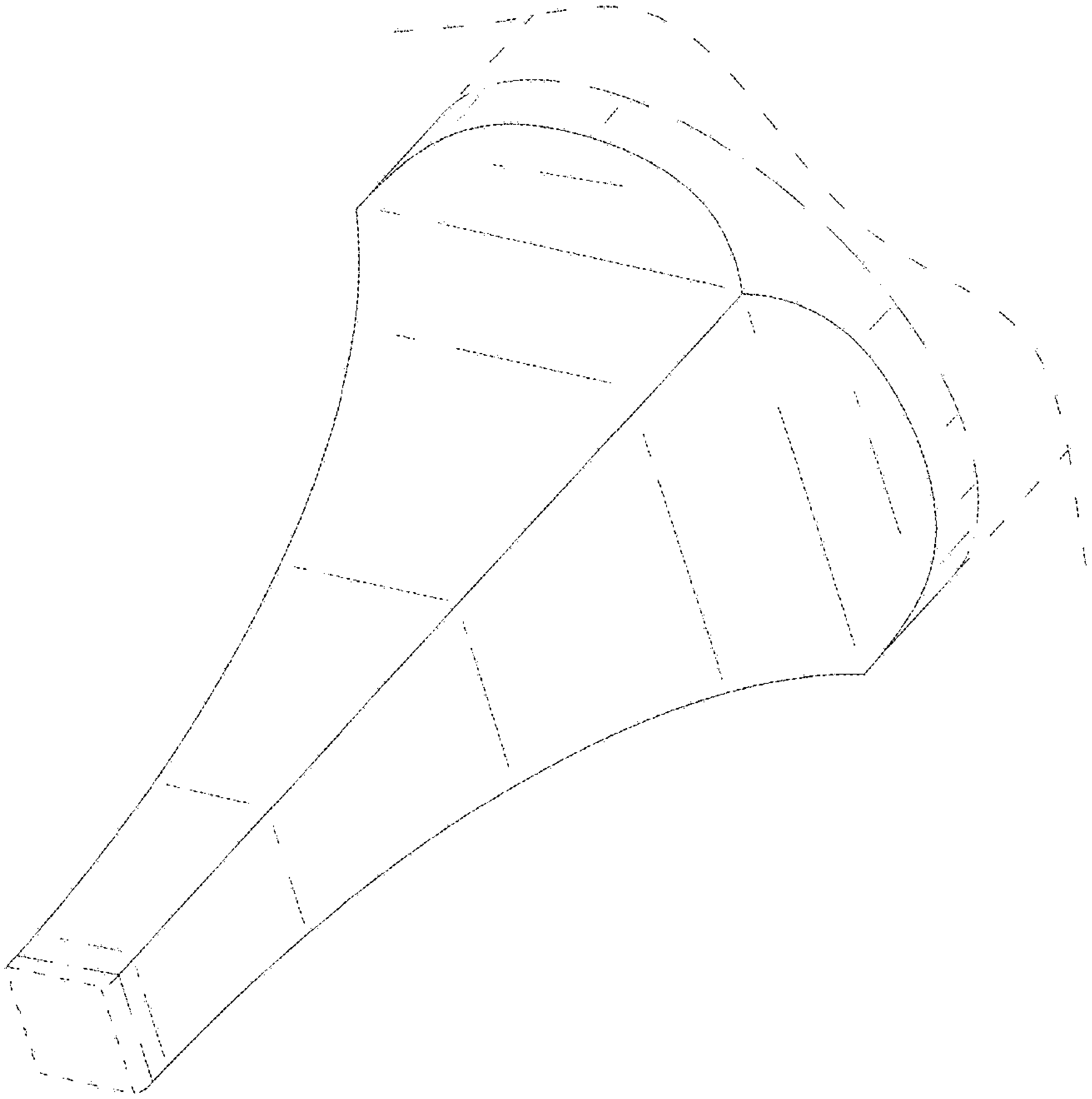

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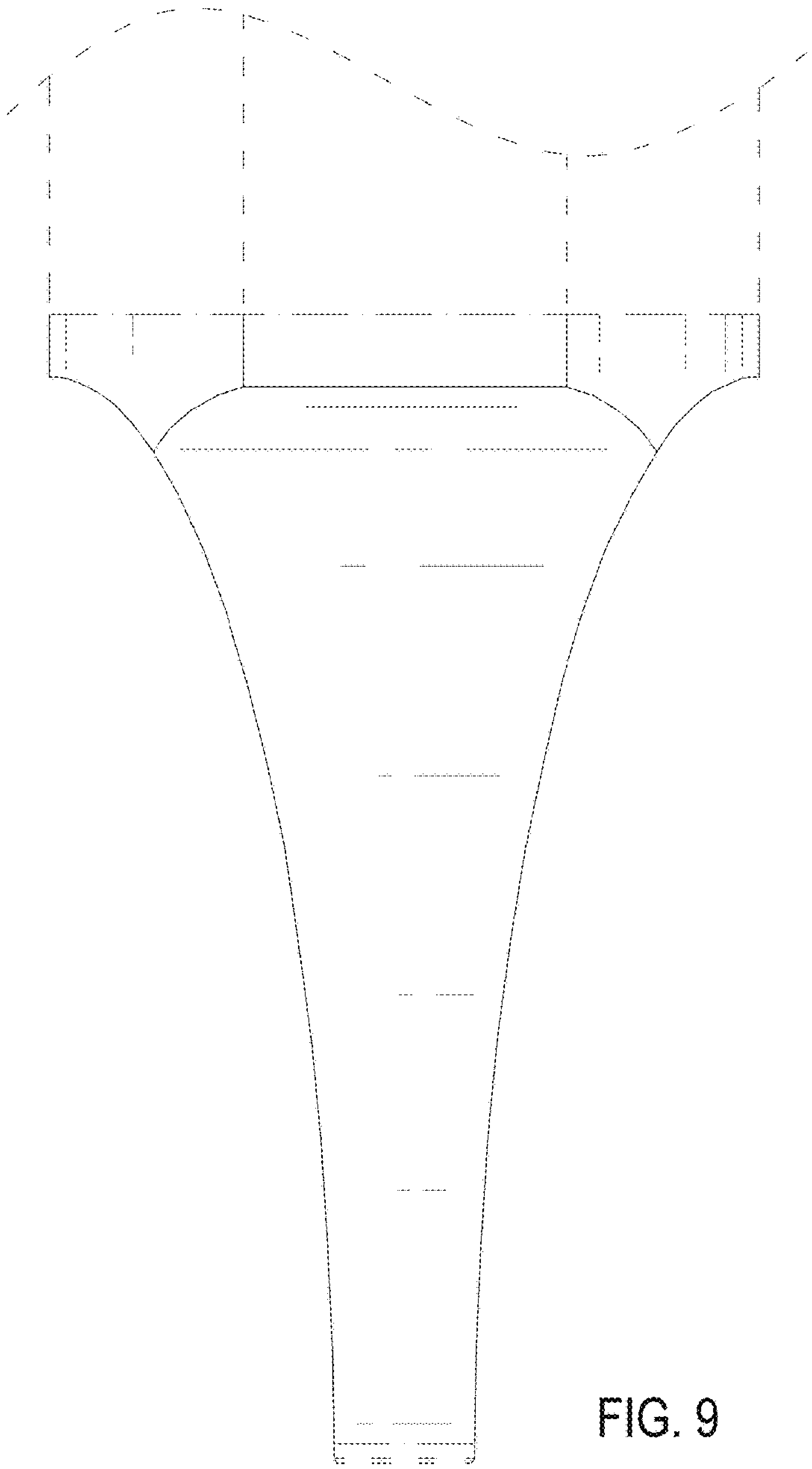

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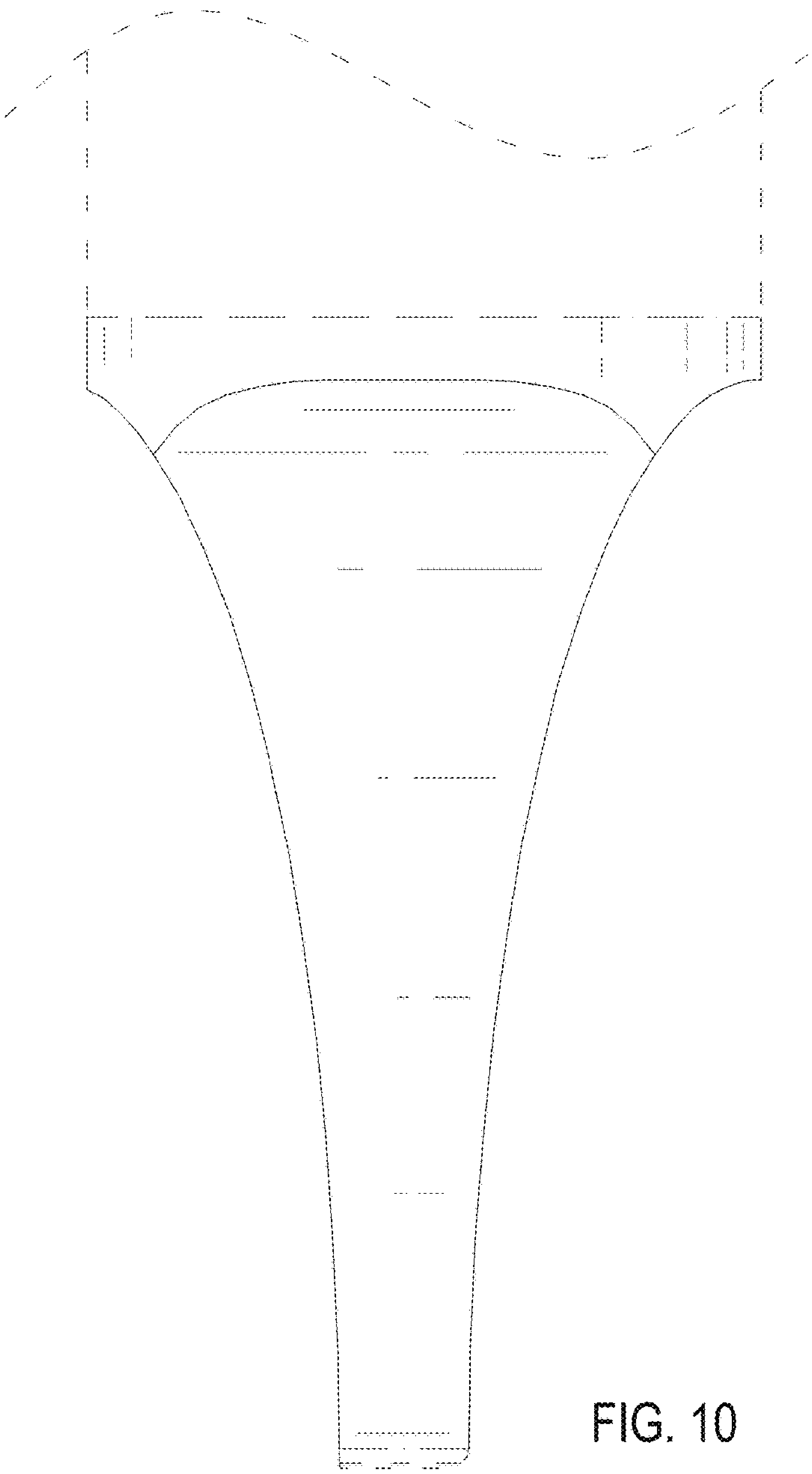
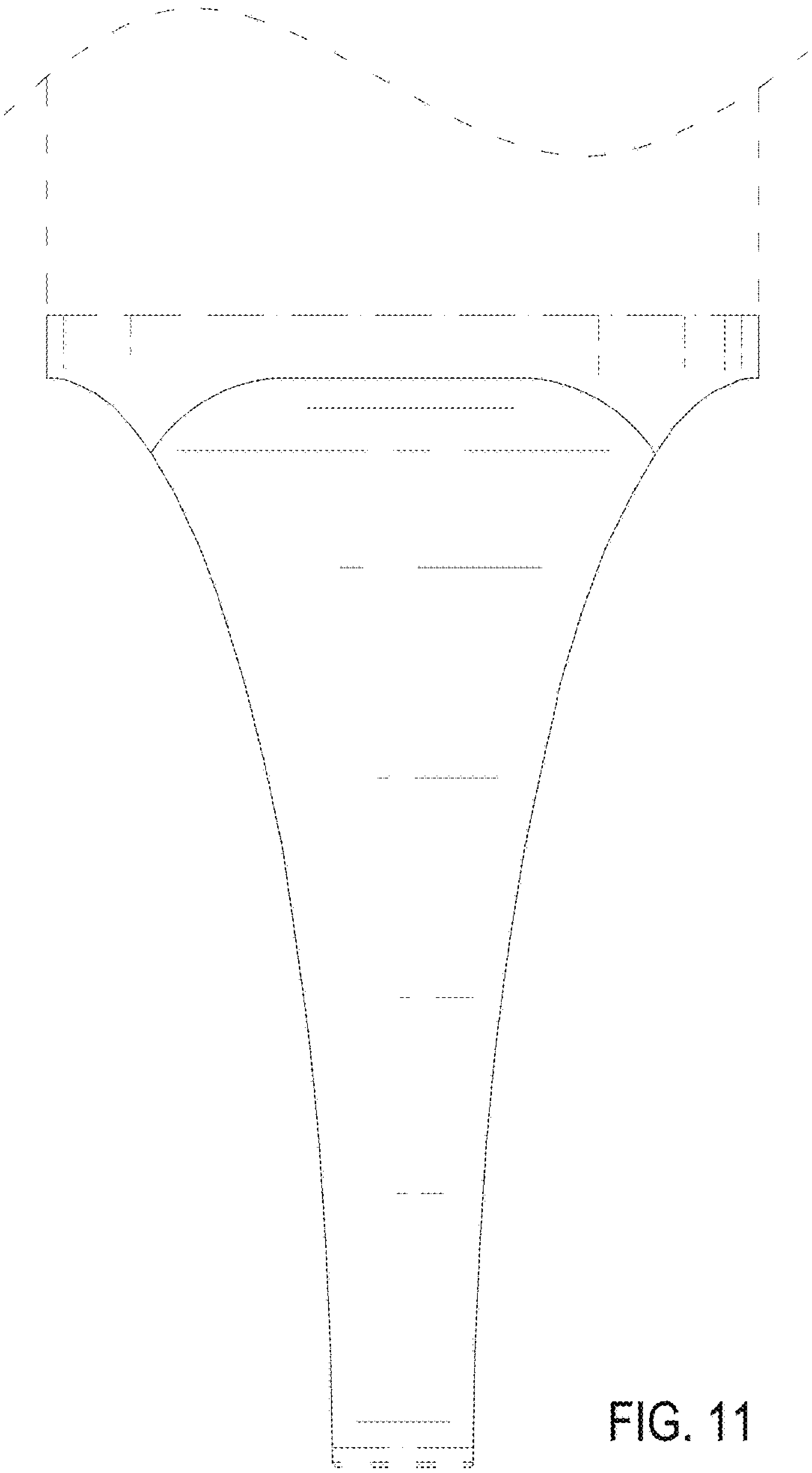


FIG. 10



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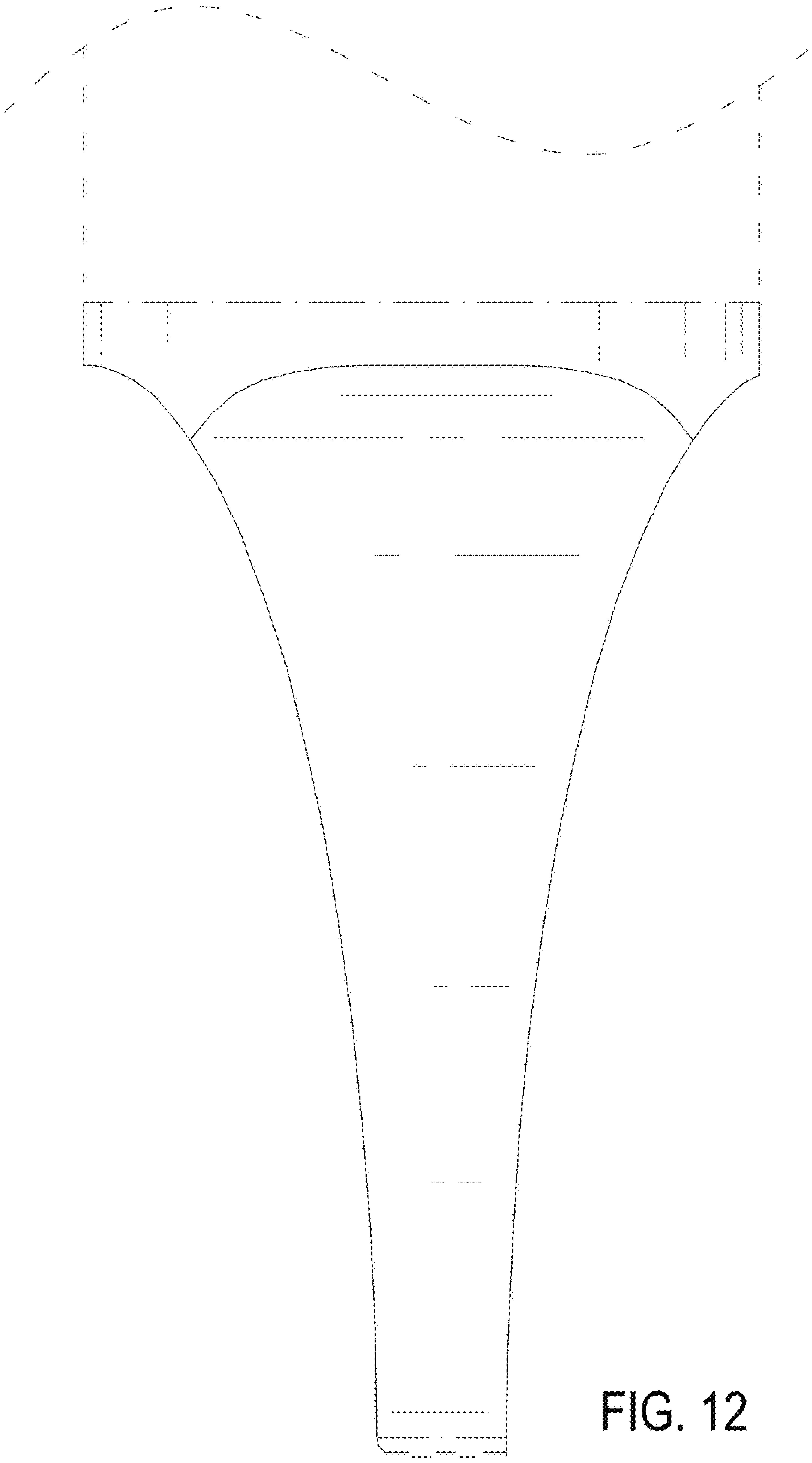

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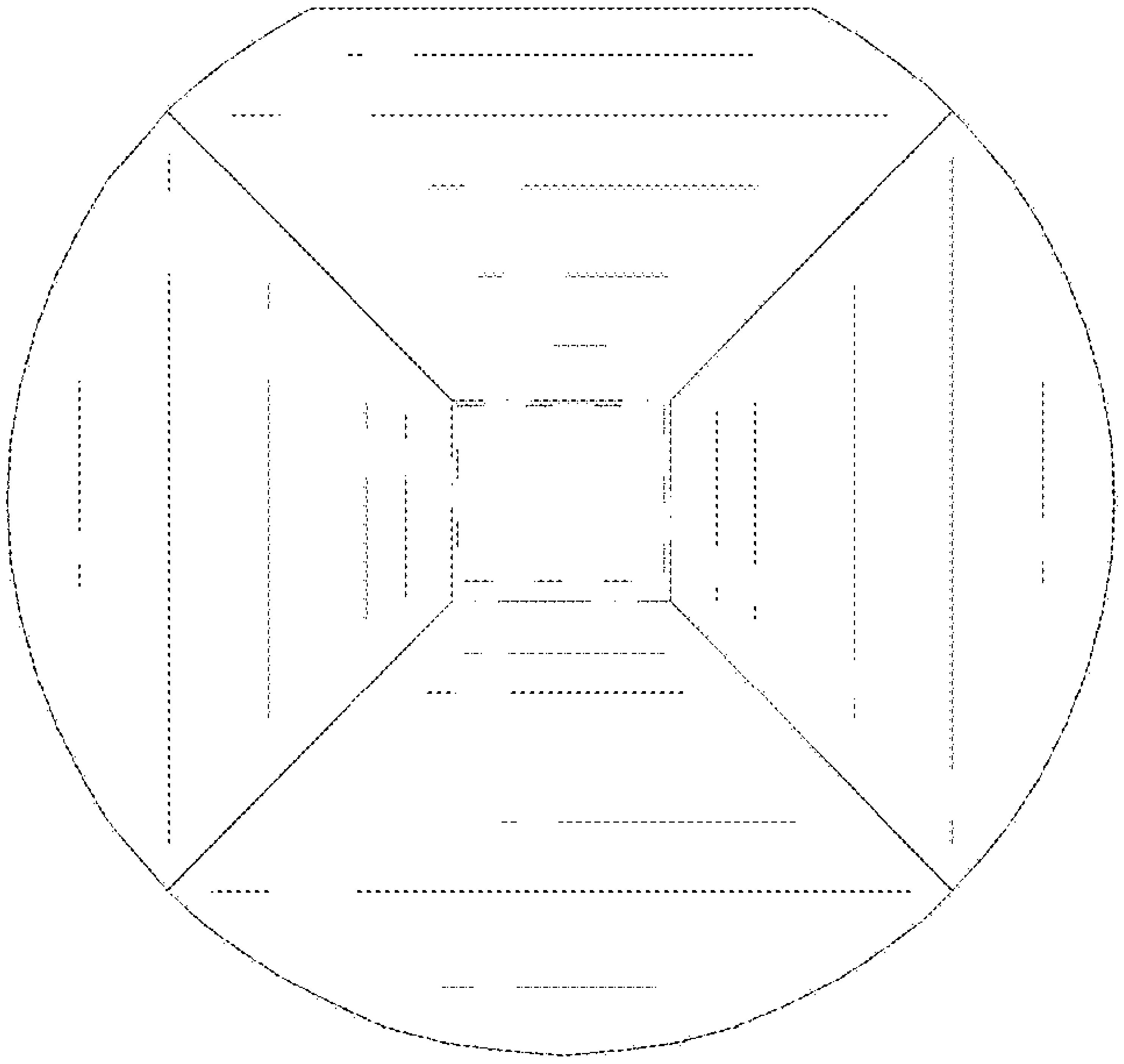

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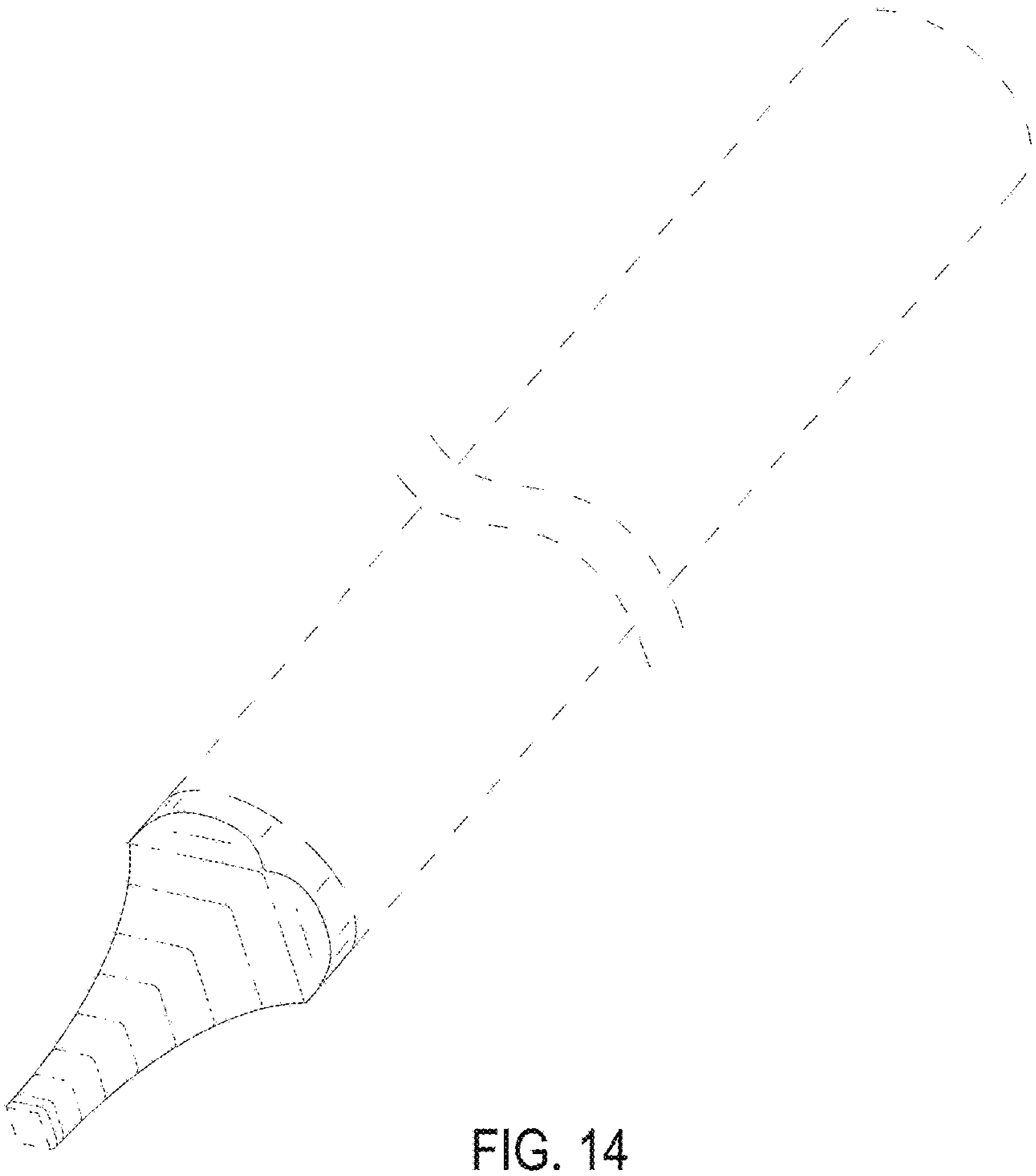

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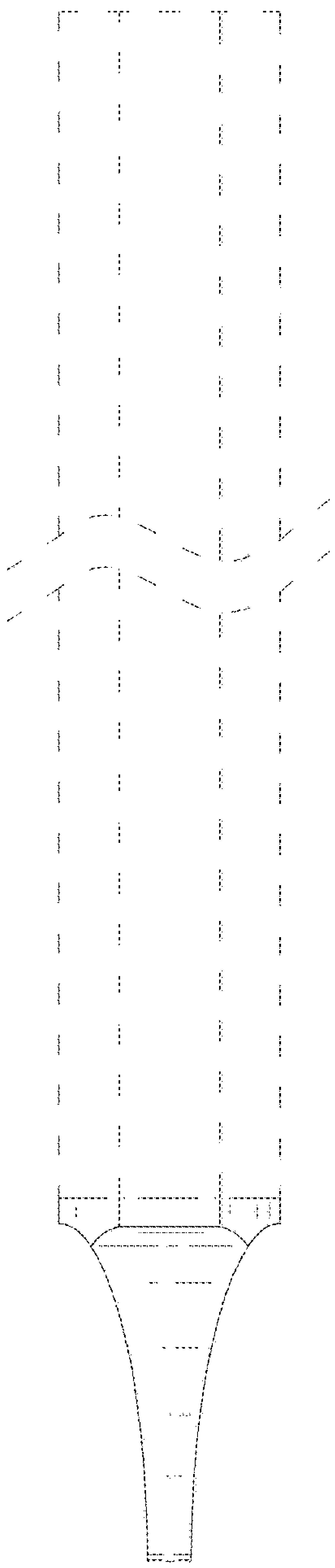

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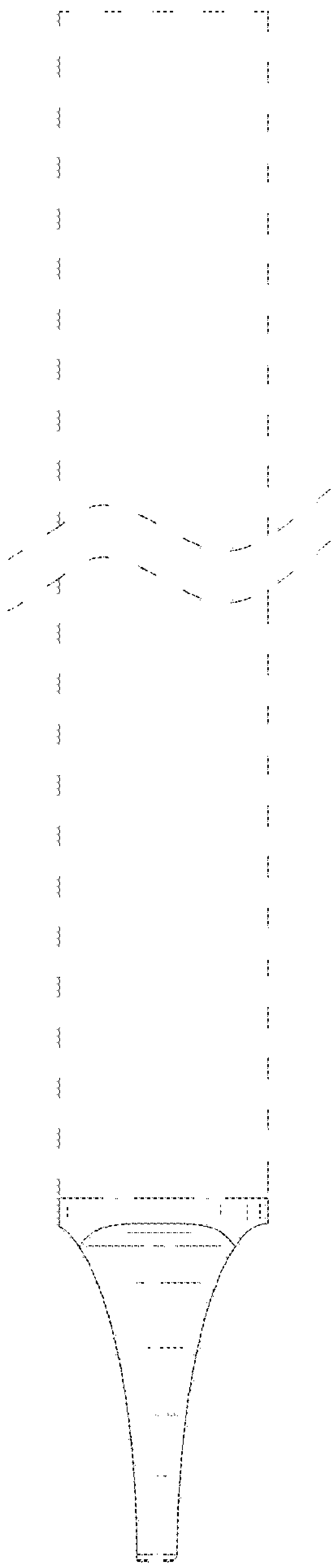

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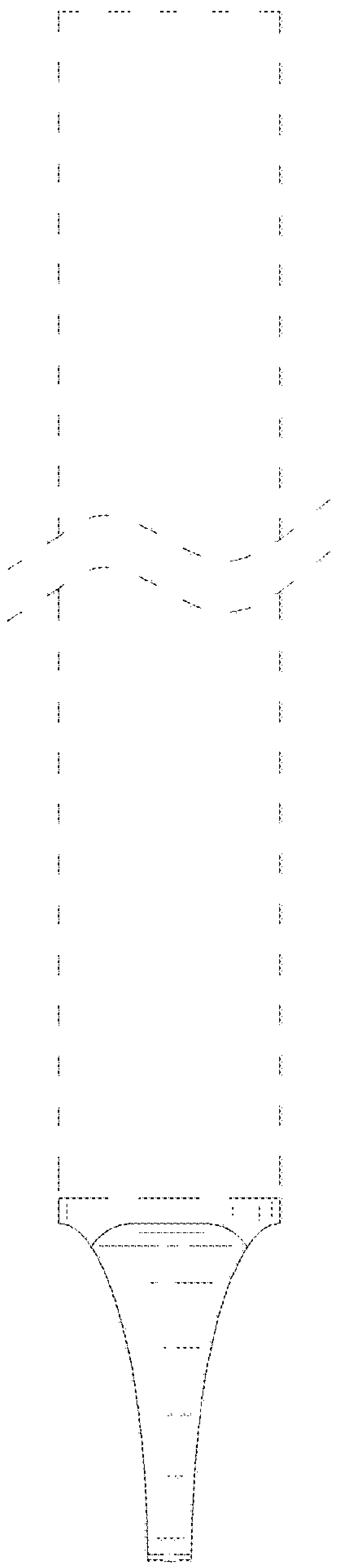

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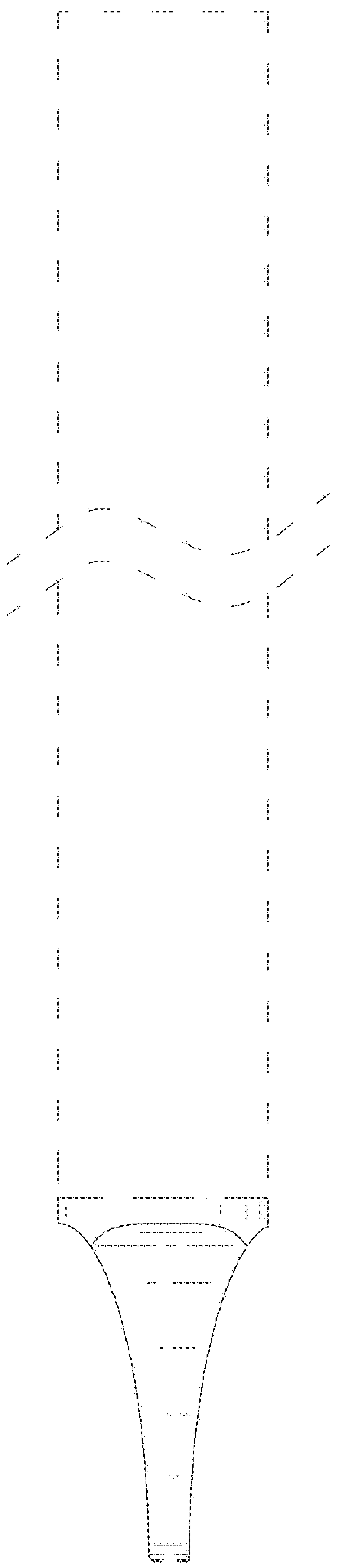

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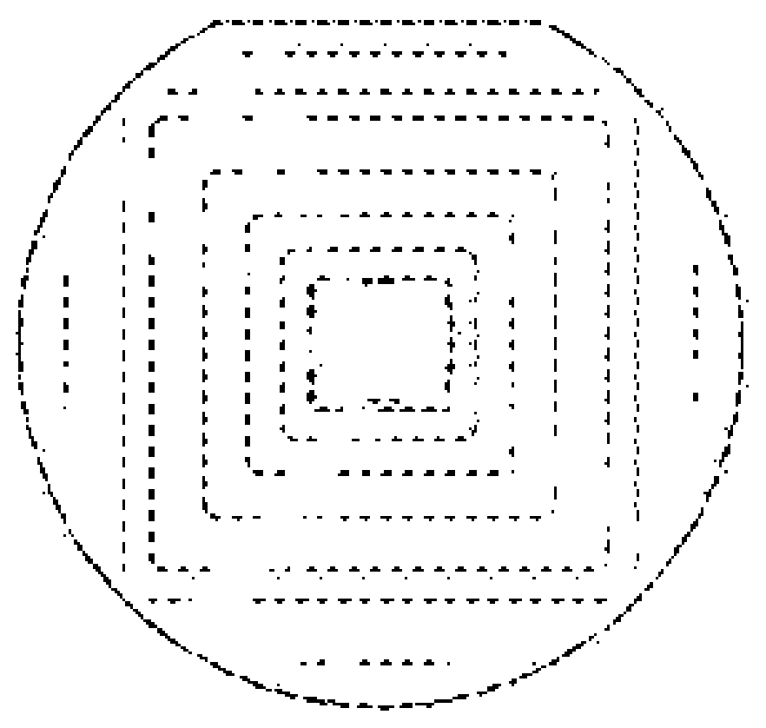

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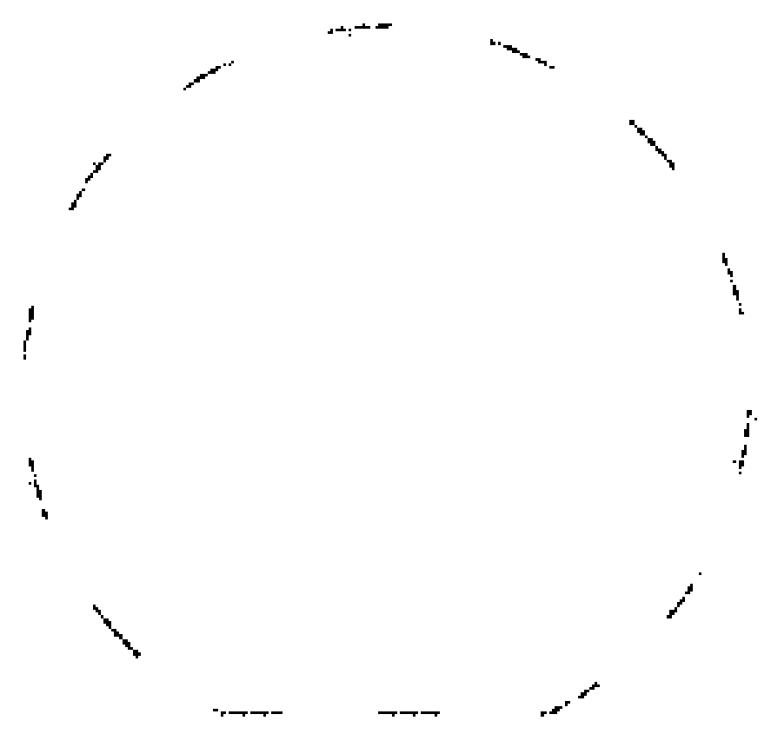

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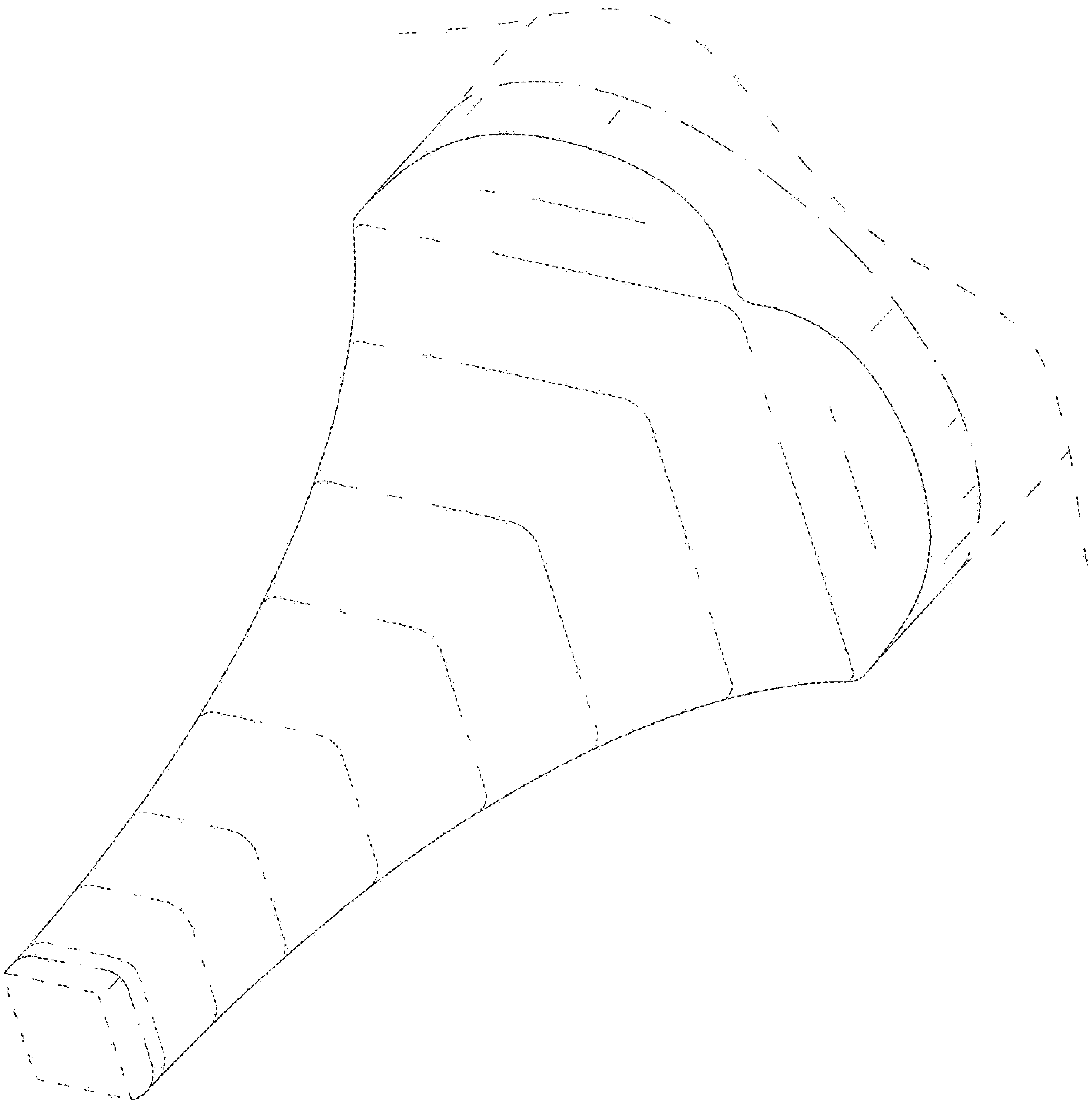
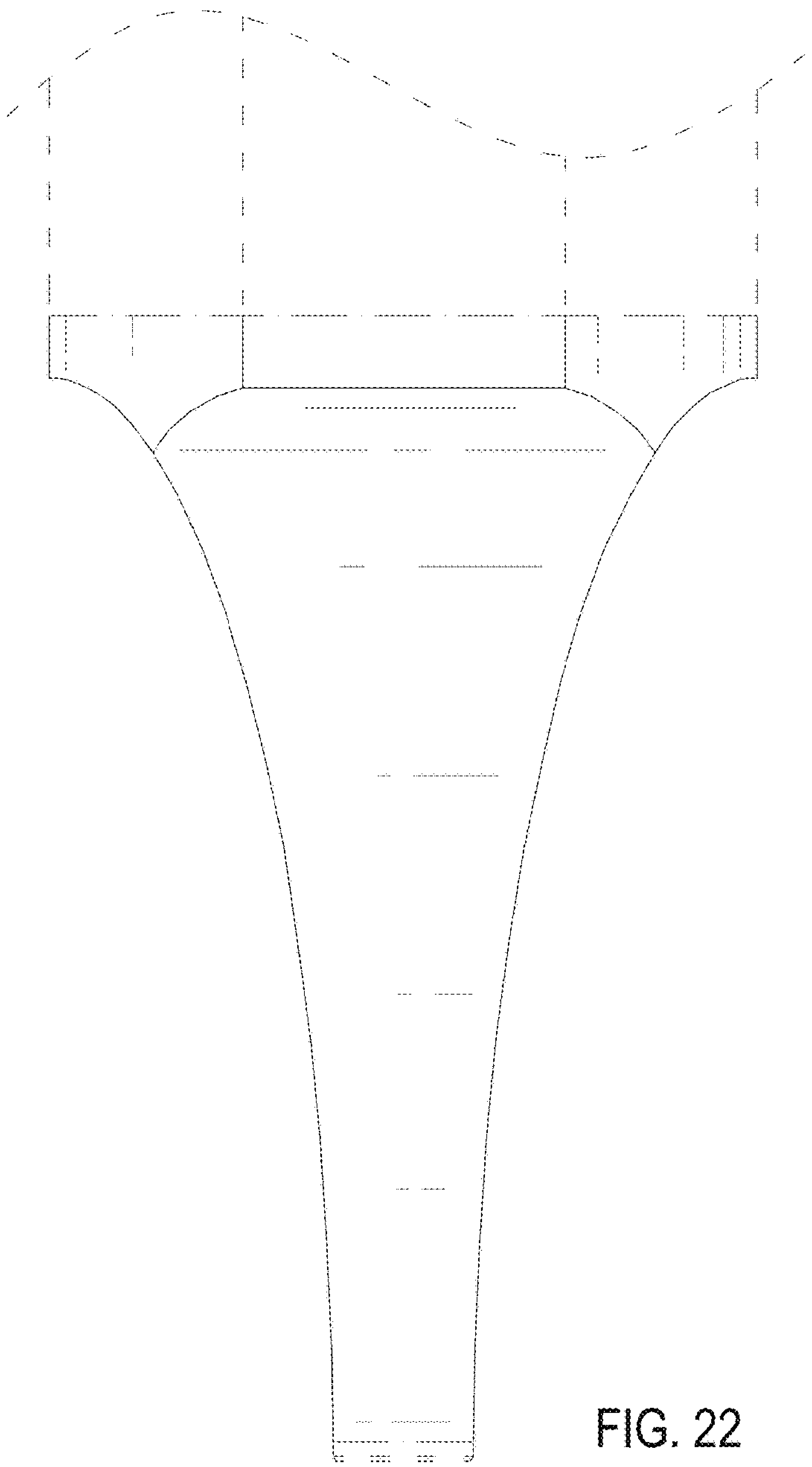


FIG. 21



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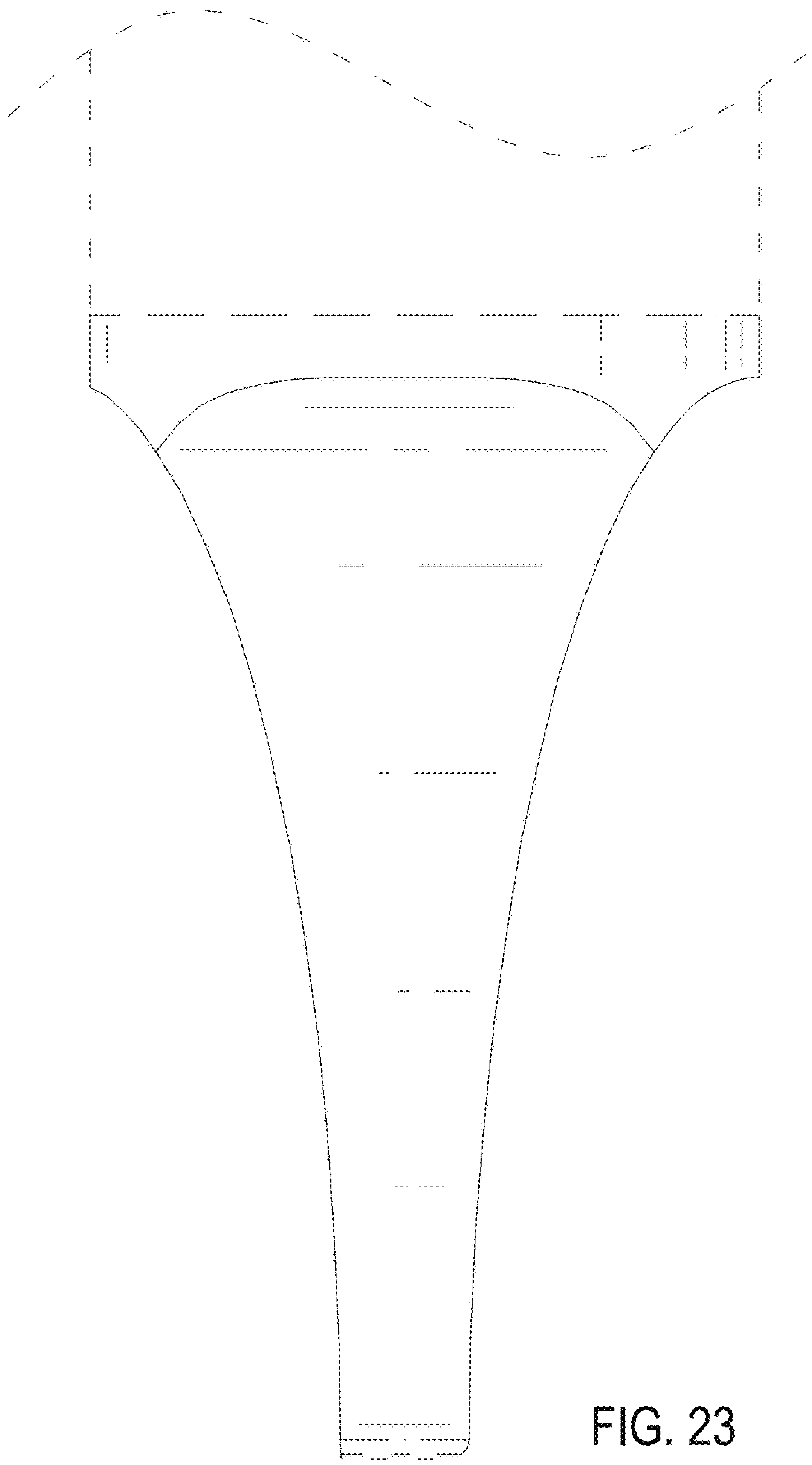

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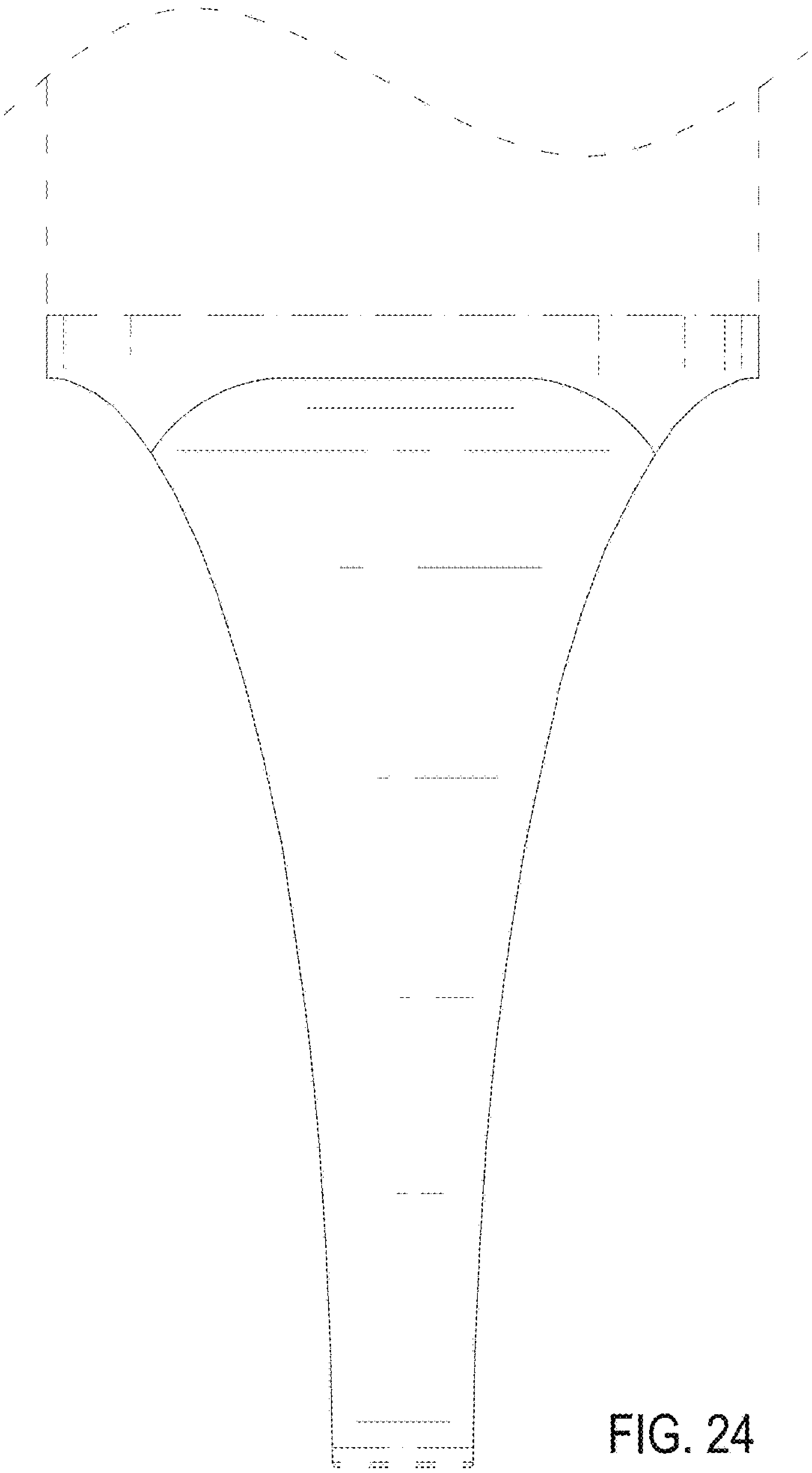

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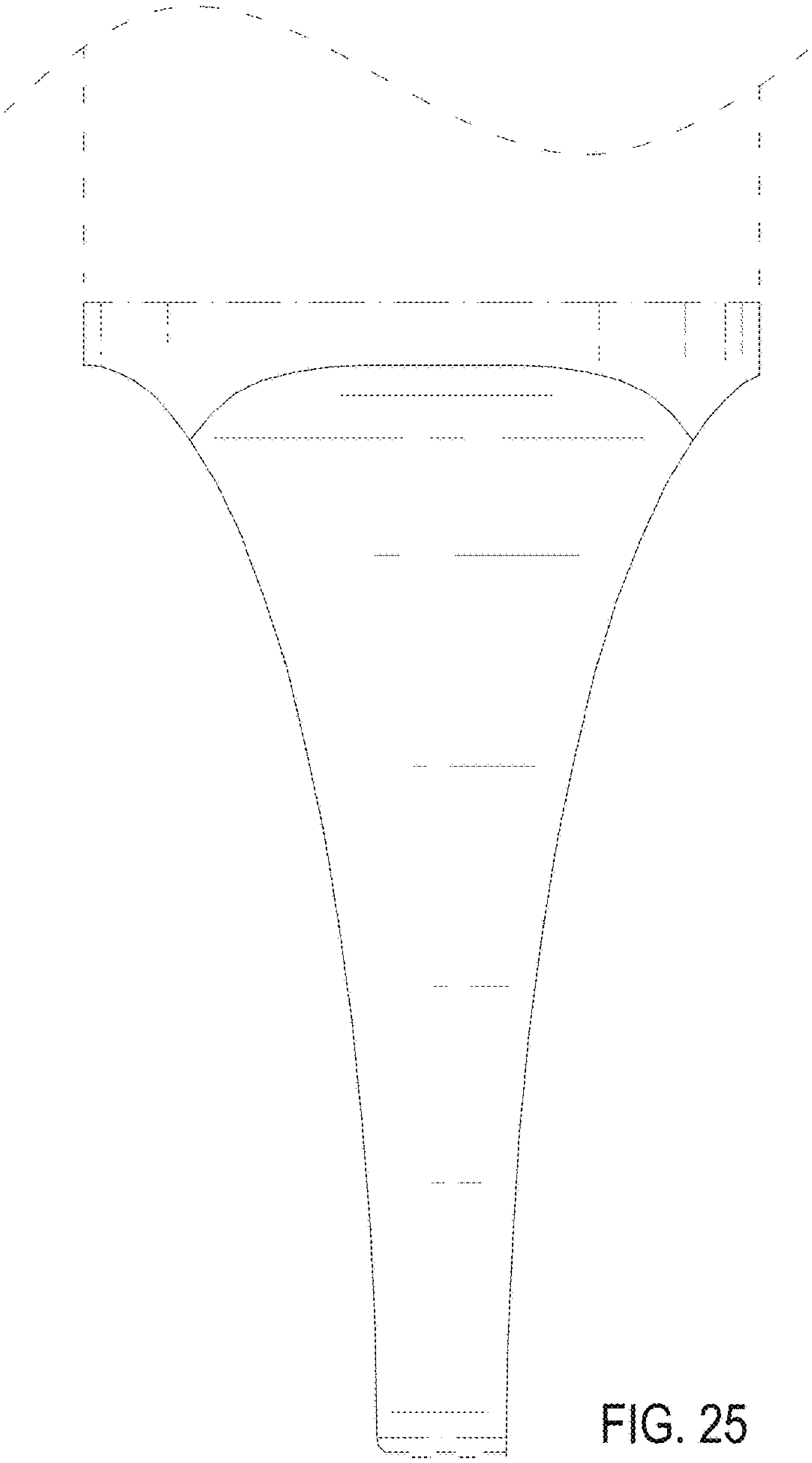

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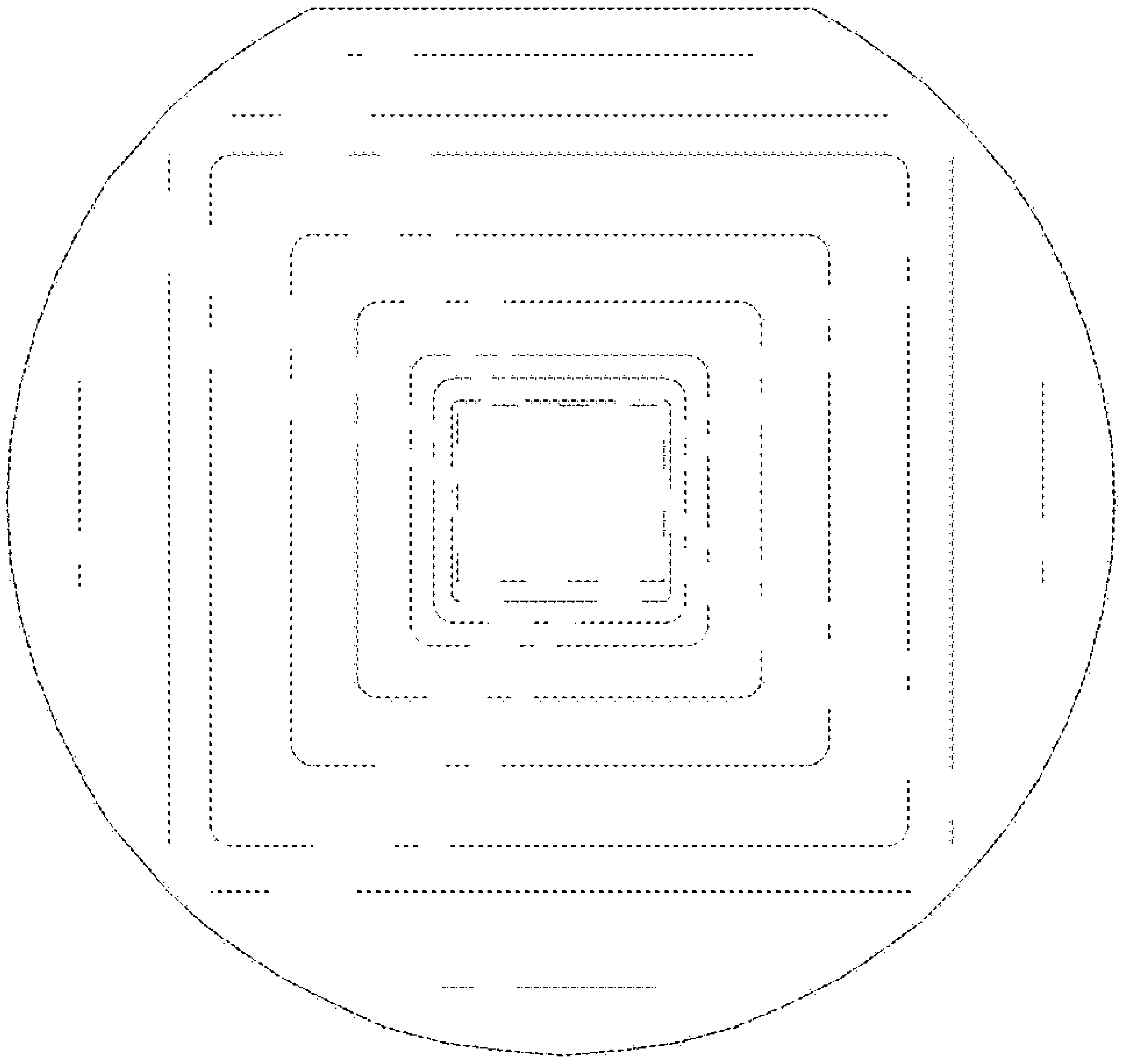

FIG. 26